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**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064stc44-10n

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The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			<b>√</b> (1)
Open-drain output option			<b>✓</b>
Fast input registers		<b>✓</b>	✓
Six global output enables		<b>✓</b>	✓
Two global clocks		✓	✓
Slew-rate control		<b>✓</b>	✓
MultiVolt interface (2)	✓	<b>✓</b>	<b>✓</b>
Programmable register	✓	<b>✓</b>	✓
Parallel expanders	<b>✓</b>	✓	✓
Shared expanders	<b>✓</b>	<b>✓</b>	<b>✓</b>
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	<b>✓</b>	✓	✓

#### Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

# Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

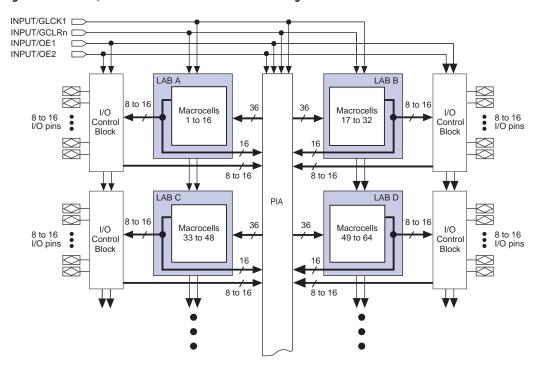


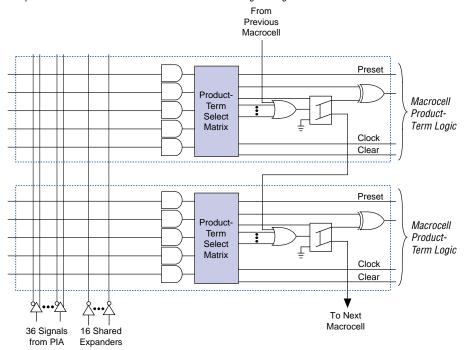
Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay ( $t_{PEXP}$ ). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by  $2 \times t_{PEXP}$ .

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.



When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to  $V_{CC}$ , the output is enabled.

The MAX 7000 architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

# In-System Programmability (ISP)

MAX 7000S devices are in-system programmable via an industry-standard 4-pin Joint Test Action Group (JTAG) interface (IEEE Std. 1149.1-1990). ISP allows quick, efficient iterations during design development and debugging cycles. The MAX 7000S architecture internally generates the high programming voltage required to program EEPROM cells, allowing in-system programming with only a single 5.0 V power supply. During in-system programming, the I/O pins are tri-stated and pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k%.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a printed circuit board with standard in-circuit test equipment before they are programmed. MAX 7000S devices can be programmed by downloading the information via in-circuit testers (ICT), embedded processors, or the Altera MasterBlaster, ByteBlasterMV, ByteBlaster, BitBlaster download cables. (The ByteBlaster cable is obsolete and is replaced by the ByteBlasterMV cable, which can program and configure 2.5-V, 3.3-V, and 5.0-V devices.) Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling and allows devices to be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. Because some in-circuit testers cannot support an adaptive algorithm, Altera offers devices tested with a constant algorithm. Devices tested to the constant algorithm have an "F" suffix in the ordering code.

The Jam<sup>TM</sup> Standard Test and Programming Language (STAPL) can be used to program MAX 7000S devices with in-circuit testers, PCs, or embedded processor.

The programming times described in Tables 6 through 8 are associated with the worst-case method using the enhanced ISP algorithm.

Table 6. MAX 7000S t <sub>PU</sub>	able 6. MAX 7000S t <sub>PULSE</sub> & Cycle <sub>TCK</sub> Values											
Device	Progra	ımming	Stand-Alone Verification									
	t <sub>PPULSE</sub> (s)	Cycle <sub>PTCK</sub>	t <sub>VPULSE</sub> (s)	Cycle <sub>VTCK</sub>								
EPM7032S	4.02	342,000	0.03	200,000								
EPM7064S	4.50	504,000	0.03	308,000								
EPM7128S	5.11	832,000	0.03	528,000								
EPM7160S	5.35	1,001,000	0.03	640,000								
EPM7192S	5.71	1,192,000	0.03	764,000								
EPM7256S	6.43	1,603,000	0.03	1,024,000								

Tables 7 and 8 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies													
Device		f <sub>TCK</sub>											
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz					
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s				
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	S				
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	S				
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	S				
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	S				
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S				

Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies														
Device		f <sub>TCK</sub>												
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz						
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s					
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	S					
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	S					
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	S					
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	S					
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	S					

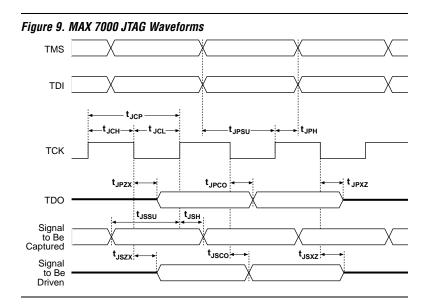


Figure 9 shows the timing requirements for the JTAG signals.

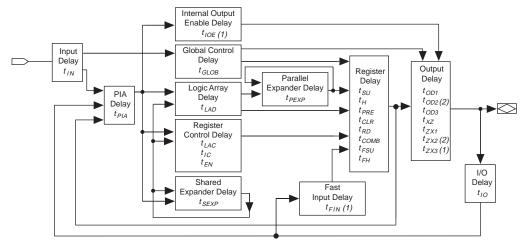
Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period	100		ns
t <sub>JCH</sub>	TCK clock high time	50		ns
t <sub>JCL</sub>	TCK clock low time	50		ns
t <sub>JPSU</sub>	JTAG port setup time	20		ns
t <sub>JPH</sub>	JTAG port hold time	45		ns
t <sub>JPCO</sub>	JTAG port clock to output		25	ns
t <sub>JPZX</sub>	JTAG port high impedance to valid output		25	ns
t <sub>JPXZ</sub>	JTAG port valid output to high impedance		25	ns
t <sub>JSSU</sub>	Capture register setup time	20		ns
t <sub>JSH</sub>	Capture register hold time	45		ns
t <sub>JSCO</sub>	Update register clock to output		25	ns
t <sub>JSZX</sub>	Update register high impedance to valid output		25	ns
t <sub>JSXZ</sub>	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (*IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*).

Figure 12. MAX 7000 Timing Model



#### Notes:

- (1) Only available in MAX 7000E and MAX 7000S devices.
- (2) Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.



For more infomration, see *Application Note* 94 (Understanding MAX 7000 *Timing*).

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	Unit		
			Min	Max	Min	Max		
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns	
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns	
t <sub>SU</sub>	Global clock setup time		5.0		6.0		ns	
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns	
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	2.5		3.0		ns	
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.5		0.5		ns	
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns	
t <sub>CH</sub>	Global clock high time		2.5		3.0		ns	
t <sub>CL</sub>	Global clock low time		2.5		3.0		ns	
t <sub>ASU</sub>	Array clock setup time		2.5		3.0		ns	
t <sub>AH</sub>	Array clock hold time		2.0		2.0		ns	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns	
t <sub>ACH</sub>	Array clock high time		3.0		3.0		ns	
t <sub>ACL</sub>	Array clock low time		3.0		3.0		ns	
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns	
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns	
t <sub>CNT</sub>	Minimum global clock period			6.6		8.0	ns	
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	151.5		125.0		MHz	
t <sub>ACNT</sub>	Minimum array clock period			6.6		8.0	ns	
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	151.5		125.0		MHz	
f <sub>MAX</sub>	Maximum clock frequency	(6)	200		166.7		MHz	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (7) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 2	77. EPM7032\$ External Time	ing Parameter	s (Part	1 of 2	<b>)</b> No	ote (1)						
Symbol	Parameter	Conditions	Speed Grade									
			-	5	-	6	-	7	-1	10		
			Min	Max	Min	Max	Min	Max	Min	Max		
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t <sub>SU</sub>	Global clock setup time		2.9		4.0		5.0		7.0		ns	
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns	
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns	
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns	
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns	
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns	
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		2.0		ns	
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.7		3.0		ns	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns	
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns	
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns	
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns	
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t <sub>CNT</sub>	Minimum global clock period			5.7		7.0		8.6		10.0	ns	
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz	
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.0		8.6		10.0	ns	

Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions	ons Speed Grade L								
			-	-5 -6 -7 -10							
			Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 2	8. EPM7032\$ Internal Tim	ing Parameter	rs /	Note (1)							
Symbol	Parameter	Conditions				Speed	Grade	)			Unit
			_	-5 -6 -7 -10							
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>FIN</sub>	Fast input delay			2.2		2.1		2.5		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.1		3.8		4.6		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.9		1.1		1.4		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.3		4.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			2.5		3.3		4.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t <sub>SU</sub>	Register setup time		0.8		1.0		1.3		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.5		3.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
$t_{RD}$	Register delay			1.2		1.6		1.9		2.0	ns
$t_{COMB}$	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t <sub>IC</sub>	Array clock delay			2.7		3.4		4.2		5.0	ns
t <sub>EN</sub>	Register enable time			2.6		3.3		4.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.6		1.4		1.7		1.0	ns
t <sub>PRE</sub>	Register preset time			2.0		2.4		3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			2.0		2.4		3.0		3.0	ns

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

Tables 33 and 34 show the EPM7160S AC operating conditions.

Table 3	33. EPM7160S External Timi	ng Parameters	(Part	1 of 2)	No	nte (1)					
Symbol	Parameter	Conditions	Speed Grade								
			-	6	-	7	-1	0	-1	15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		3.4		4.2		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.9		1.1		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.7		2.1		3.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)												
Symbol	Parameter	Conditions		Speed Grade							Unit	
			-	6	-	7	-1	0	-1	15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t <sub>CLR</sub>	Register clear time			2.4		3.0		3.0		4.0	ns	
t <sub>PIA</sub>	PIA delay	(7)		1.6		2.0		1.0		2.0	ns	
t <sub>LPA</sub>	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns	

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)									
Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		1
			Min	Max	Min	Max	Min	Max	1
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		4.1		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t <sub>CH</sub>	Global clock high time		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		1.0		2.0		4.0		ns

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

# Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$  in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I<sub>CCINT</sub> value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{USED}$$

The parameters in this equation are shown below:

 $MC_{TON}$  = Number of macrocells with the Turbo Bit option turned on,

as reported in the MAX+PLUS II Report File (.rpt)

 $MC_{DEV}$  = Number of macrocells in the device

MC<sub>USED</sub> = Total number of macrocells in the design, as reported

in the MAX+PLUS II Report File (.rpt)

 $f_{MAX}$  = Highest clock frequency to the device

tog<sub>LC</sub> = Average ratio of logic cells toggling at each clock

(typically 0.125)

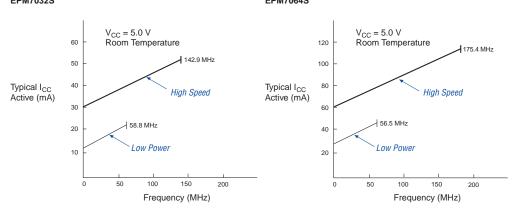
A, B, C = Constants, shown in Table 39

Table 39. MAX 7000 I <sub>CC</sub> Equation Constants									
Device	Α	В	С						
EPM7032	1.87	0.52	0.144						
EPM7064	1.63	0.74	0.144						
EPM7096	1.63	0.74	0.144						
EPM7128E	1.17	0.54	0.096						
EPM7160E	1.17	0.54	0.096						
EPM7192E	1.17	0.54	0.096						
EPM7256E	1.17	0.54	0.096						
EPM7032S	0.93	0.40	0.040						
EPM7064S	0.93	0.40	0.040						
EPM7128S	0.93	0.40	0.040						
EPM7160S	0.93	0.40	0.040						
EPM7192S	0.93	0.40	0.040						
EPM7256S	0.93	0.40	0.040						

This calculation provides an  $I_{CC}$  estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual  $I_{CC}$  values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figure 15 shows typical supply current versus frequency for MAX 7000S devices.





#### EPM7128S EPM7160S

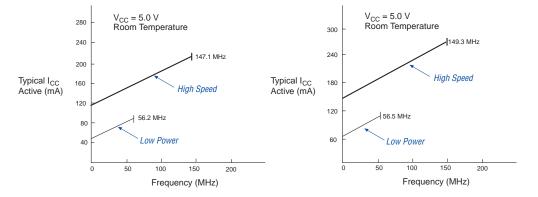
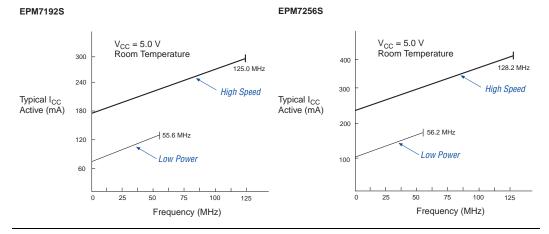


Figure 15. I<sub>CC</sub> vs. Frequency for MAX 7000S Devices (Part 2 of 2)



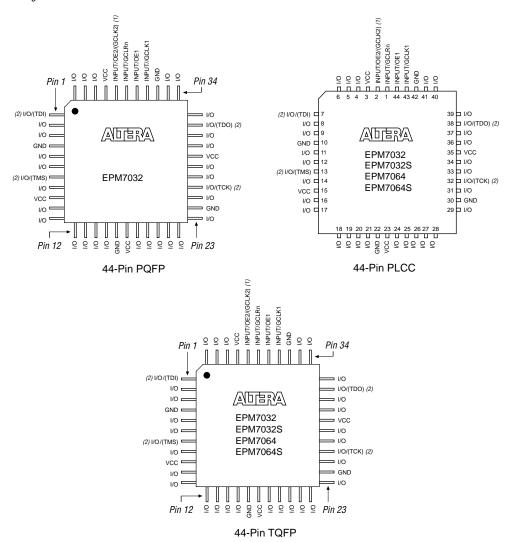
# Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.

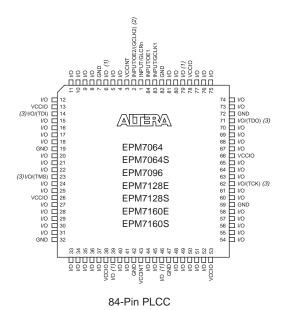


#### Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

### Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



#### Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

## Figure 21. 192-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

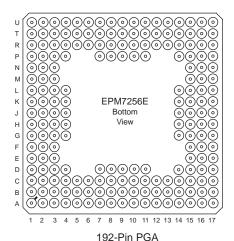


Figure 22. 208-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

